

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	162	fiber adj glass adj board	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/30 09:37
L3	4	isolating adj carrier adj layer	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/30 10:13
L4	11151	carrier adj layer	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/30 10:13
L5	4	carrier adj layer near3 gauze	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/30 10:13
L6	6719	carrier adj layer	US-PGPUB; USPAT; USOCR	OR	ON	2007/01/30 10:38
L7	0	6 and 1	US-PGPUB; USPAT; USOCR	OR	ON	2007/01/30 10:39
L8	94	carrier adj layer and gauze	US-PGPUB; USPAT; USOCR	OR	ON	2007/01/30 10:39
L9	0	6 and 1	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/30 10:39

EAST Search History

L10	99	carrier adj layer and gauze	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/30 10:39
L11	5	carrier adj layer near4 gauze	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/30 10:41
L12	22	carrier adj layer with gauze	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/30 10:42
L13	29	carrier adj layer same gauze	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/30 10:42
S1	13466067	DE "21" "04" "262"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/26 16:54
S2	7470065	DE "2104262"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/26 16:54
S4	0	DE2104262A	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/26 16:56

EAST Search History

S5	2	"2002117743"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/26 16:57
S6	0	"2002/117743"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/26 16:57
S7	101	ashahi toshyuki	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/26 16:58
S8	99	ashahi toshyuki and "2002"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/26 16:59
S9	100	ashahi toshyuki.inv.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/26 16:59
S10	2	"2002117743"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/26 17:01
S11	3	ashahi.inv.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/26 17:02

EAST Search History

S12	9	"6324072"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/26 17:03
S13	2	2104262A	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/30 10:11
S14	0	("2002117743").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/01/26 17:05
S15	0	"2002117743"	US-PGPUB; USPAT; IBM_TDB	OR	ON	2007/01/26 17:06
S16	1	"2002117743"	US-PGPUB; USPAT; DERWENT; IBM_TDB	OR	ON	2007/01/26 17:08
S17	12454	toshiyuki	US-PGPUB; USPAT; DERWENT; IBM_TDB	OR	ON	2007/01/26 17:09
S18	59	(asahi toshiyuki).inv.	US-PGPUB; USPAT; DERWENT; IBM_TDB	ADJ	ON	2007/01/29 09:32
S19	2	"6300161".pn.	US-PGPUB; USPAT; DERWENT; IBM_TDB	ADJ	ON	2007/01/29 09:32
S20	9	("5134539" "5135889" "5583739" "5633785" "5729047" "5872697" "5874770" "5973910" "6075711").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/01/29 09:57
S21	128208	((first or one) adj layer) and ((second or two or other) adj layer) and (electroconductive or conductive or conductor\$1 or conducting) (encapsulation or encapsulating or passivating) and (contact)	US-PGPUB; USPAT; USOCR	OR	ON	2007/01/29 10:04

EAST Search History

S22	35497	S21 and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2007/01/29 10:02
S23	24167	S22 and pattern\$4	US-PGPUB; USPAT; USOCR	OR	ON	2007/01/29 10:03
S24	1866	S23 and foil	US-PGPUB; USPAT; USOCR	OR	ON	2007/01/29 10:03
S25	1640	S24 and (semiconductor or semiconductive)	US-PGPUB; USPAT; USOCR	OR	ON	2007/01/29 10:03
S26	1387	S25 and (connection)	US-PGPUB; USPAT; USOCR	OR	ON	2007/01/29 10:04
S27	73889	((first or one) adj layer) and ((second or two or other) adj layer) and (electroconductive or conductive or conductor\$1 or conducting) (encapsulation or encapsulating or passivating) and (contact) and pattern\$4 and (semiconductive or semiconductor)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 10:16
S28	28824	S27 and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 10:16
S29	28824	S28 and ad<"20050615" and prad< "20021220" and rlad<"20021220"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 10:30
S30	2	"6324072".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 10:18

EAST Search History

S31	20	("4855867" "4922376" "4984358" "5203075" "5426263" "5438224" "5495397" "5535512" "5625230" "5838067" "5952725" "5969944" "6054337" "6144101").PN. OR ("6324072").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/01/29 10:19
S32	281174	asahi toshiyuki.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 10:20
S33	93391	toshiyuki.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 10:20
S34	4003	asahi.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 10:21
S35	4003	asahi.inv.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 10:21
S36	4003	asahi.inv. and ad<"20020829"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 10:21
S37	4003	asahi.in. and ad<"20020829"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 10:21

EAST Search History

S38	2	"2002117743"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 10:23
S39	4003	asahi.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 10:23
S40	4003	S39 and ad<"20020829"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 10:23
S41	530	S39 and "2002"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 11:05
S42	73889	((first or one) adj layer) and ((second or two or other) adj layer) and (electroconductive or conductive or conductor\$1 or conducting) (encapsulation or encapsulating or passivating) and (contact) and pattern\$4 and (semiconductive or semiconductor)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 10:30
S43	20	("4855867" "4922376" "4984358" "5203075" "5426263" "5438224" "5495397" "5535512" "5625230" "5838067" "5952725" "5969944" "6054337" "6144101").PN. OR ("6324072").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/01/29 10:45
S44	1	"5203075".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2007/01/29 10:55
S45	1	"5350947".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2007/01/30 10:38

EAST Search History

S46	0	"2002074146"	US-PGPUB; USPAT; USOCR	OR	ON	2007/01/29 10:57
S47	3	"2002074146"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 10:57
S48	3	"2001048156"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 10:58
S49	3	"2002261449"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 11:02
S50	2	"6734542".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 11:02
S51	12	("5172304" "6038133" "6060150" "6160526").PN. OR ("6734542").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/01/29 11:04
S52	25068	encapsulat\$4 and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 11:08
S53	25068	encapsulat\$4 and "257"/\$.ccls. and rlad<"20021220"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 11:31

EAST Search History

S54	2	"20020117743"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 13:08
S55	852	(pcb or printed adj circuit adj board) near4 (encapsulant or encapsulation or encapsulating)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 13:24
S56	852	(pcb or printed adj circuit adj board) near4 (encapsulant or encapsulation or encapsulating) and ad<"20050615" and prad<"20021220"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 13:27
S57	852	(pcb or printed adj circuit adj board) near4 (encapsulant or encapsulation or encapsulating) and ad<"20021220"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 13:53
S58	852	(pcb or printed adj circuit adj board) near4 (encapsulant or encapsulation or encapsulating)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 13:29
S59	616	(pcb or printed adj circuit adj board) near4 (encapsulant or encapsulation or encapsulating) and @ad<"20021220"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 13:29
S60	28	(pcb or printed adj circuit adj board) near4 (encapsulant or encapsulation or encapsulating) and @ad<"20050615" and @prad<"20021220" and @rlad<"20021220"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 13:38

EAST Search History

S61	232	(passivation or passivating) adj layer near4 (encapsulant or encapsulation or encapsulating)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 13:39
S62	4	(passivation or passivating) adj layer near4 (encapsulant or encapsulation or encapsulating) and @ad<"20050615" and @prad<"20021220" and @rlad<"20021220"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 13:45
S63	5	"2004057662"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 13:43
S64	41	(passivation or passivating) adj layer near4 (encapsulant or encapsulation or encapsulating) and @ad<"20050615" and @prad<"20021220"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 13:50
S65	14	("5132830" "5185653" "5299041" "5539552").PN. OR ("5606194").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/01/29 13:49
S66	1	(passivation or passivating) adj layer near4 (encapsulant or encapsulation or encapsulating) and @ad<"20050615" and @prad<"20021220" and (second or two or other) adj semiconductor	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 13:51
S67	27	(pcb or printed adj circuit adj board) near4 (encapsulant or encapsulation or encapsulating) and sandwich	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 13:55

EAST Search History

S68	4	09/997,937	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 13:55
S69	2	"0615289"	US-PGPUB; USPAT; IBM_TDB	OR	ON	2007/01/29 14:00
S70	7	"0615289"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 14:01
S71	3	"2001048156"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 14:01
S72	2	"2001352009"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 14:02
S73	2	"6324072".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 14:02
S74	20	("4855867" "4922376" "4984358" "5203075" "5426263" "5438224" "5495397" "5535512" "5625230" "5838067" "5952725" "5969944" "6054337" "6144101").PN. OR ("6324072").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/01/29 14:02
S75	1	"6324072".pn.	US-PGPUB; USPAT; IBM_TDB	OR	ON	2007/01/29 15:08

EAST Search History

S76	1	"20020117743"	US-PGPUB; USPAT; IBM_TDB	OR	ON	2007/01/29 17:10
S77	1	(detachable or detached or detach) adj layer and semiconductor adj element	US-PGPUB; USPAT; IBM_TDB	OR	ON	2007/01/29 15:43
S78	0	("2003/0127725").URPN.	USPAT	OR	ON	2007/01/29 15:38
S79	1	(detachable or detached or detach) adj layer and semiconductor adj element	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 15:59
S80	190	(detachable or detached or detach or separate) adj layer and semiconductor adj element	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 15:43
S81	2	"20020117743"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 16:20
S82	572	((isolating or isolated or isolation) adj layer\$1) and pattern\$2 adj layer	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 16:31
S83	159	S82 and @ad<"20050615" and @prad<"20021220" and rlad<"20021220"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 16:25
S84	572	((isolating or isolated or isolation) adj layer) and pattern\$2 adj layer	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 16:25

EAST Search History

S85	159	S84 and @ad<"20050615" and @prad<"20021220" and rlad<"20021220"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 16:28
S86	2	isolating adj gauze	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 16:29
S87	6	isolat\$3 adj gauze	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 16:30
S88	92	((isolating) adj layer\$1) and pattern\$2 adj layer	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 16:31
S89	46	((isolating) adj layer\$1) and patterned adj layer	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 16:46
S90	9	passivating near5 sacrificial adj layer	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 16:59
S91	0	"10539314"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 16:59

EAST Search History

S92	3	"2104262"	US-PGPUB; USPAT; IBM_TDB	OR	ON	2007/01/29 17:10
S93	12	"2104262"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/30 09:37
S94	3	"5350947".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 17:23
S95	8732	438/106,107,112,113,110,118, 127,119.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 17:24
S96	17	438/106,107,112,113,110,118, 127,119.ccls. and isolating adj layer	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/29 17:27